

Amendments to the Claims:

Following is a complete listing of the claims pending in the application, as amended:

1-37. (Cancelled)

38. (Currently Amended) A packaged microelectronic device, comprising:
a microelectronic die having an integrated circuit and a plurality of bond-pads coupled to the integrated circuit;
an interposer substrate having a first side coupled to the die, a second side opposite the first side, a plurality of ball-pads arranged on the second side to be coupled to a printed circuit board, interconnects electrically coupled to the bond-pads on the die and the ball-pads, a plurality of trace lines adjacent to the ball-pads, and a solder-mask on the second side having openings over the ball-pads, wherein at least a portion of at least one of the plurality of trace lines is exposed in the openings;
a plurality of solder-balls arranged so that each solder-ball is in an opening in the solder-mask and contacting a corresponding ball-pad; and
a dielectric compound in the openings in the solder-mask, wherein the dielectric compound surrounds a portion of the perimeter of each of the ball-pads and the solder-balls such that all the ball-pads and solder-balls are electrically insulated from any exposed portion of the plurality of trace lines.

39. (Original) The device of claim 38 wherein the dielectric compound includes a dielectric flux.

40. (Currently Amended) A packaged microelectronic device, comprising:
a microelectronic die having an integrated circuit and at least one bond-pad coupled to the integrated circuit;

an interposer substrate having a first side coupled to the die, a second side opposite the first side, a ball-pad on the second side, an interconnect electrically coupled to the bond-pad on the die and the ball-pad, a trace line adjacent to the ball-pad, and a solder-mask on the second side having an opening over the ball-pad and at least a portion of the trace line;
a solder-ball on the ball-pad; and
a dielectric compound in the opening in the solder-mask that electrically insulates the ball-pad and the solder-ball from any exposed portion of the adjacent trace line in the opening.

41. (Original) The device of claim 40 wherein the dielectric compound includes a dielectric flux.

42. (Original) The device of claim 40, further comprising a circuit board having a contact coupled to the solder-ball.

43. (Original) The device of claim 42, further comprising a eutectic paste proximate to the contact.

44. (Original) The device of claim 40, further comprising a eutectic paste proximate to the solder-ball.

45. (Original) The device of claim 40 wherein the dielectric compound in the opening covers an exposed portion of the adjacent trace line.